

RoHS HF 160 Series Fuse and Clip Assembly





Agency Approvals

AGENCY	AGENCY FILE NUMBER	AMPERE RANGE
c FU °us	E14721	0.5A - 5A

Electrical Characteristics for Series

% of Ampere Rating	Opening Time	
100%	4 hours, Minimum	
250%	120 seconds, Maximum	

Description

The 160 Series product is a metal fuse clip with preinstalled Littelfuse 443 Series Fuse. This fuse and clip combination can be automatically installed in PC Boards in one efficient manufacturing operation. It permits quick and easy fuse replacement without exposing the PC Boards and other components to risks of rework solder heat as required with direct surface mount fuses.

It is designed to enable compliance with the RoHS directive. This product is fully compatible with lead-free solder alloy and higher temperature profiles associated with lead-free assembly.

Features

- Offer low profile
 easily-replaceable fuse
 alternative compatible
 with automated
 PCB surface mount
 equipment
- Come supplied with Littelfuse 443 Series Time-Lag 250V Nano^{2®} Fuse
- RoHS compliant and Halogen Free
- Clip fully compatible with RoHS/lead-free solder alloys and higher temperature profiles associated with lead-free assembly
- 0.5A 5A ampere rating available

Applications

- AC/DC power adaptor
- Telecom equipment system power
- Portable system builtin AC/DC converter
- High voltage DC/DC converter
- Lighting System
- LED Lighting

Electrical Specifications by Item

	Ampere Rating (A)	Amp Code	Max Voltage Rating (V)	Interrupting Rating	Nominal Cold Resistance (Ohms)	Nominal Melting I²t (A²sec)	Nominal Voltage Drop (mV)	Agency Approvals
								c 71 2 us
	0.50	0.50	250		.5974	1.96	334	X
	0.75	0.75	250		.2729	2.25	223	X
	1.00	001.	250		.1826	9.00	207	X
	1.50	01.5	250		.1100	15.21	210	X
	2.00	002.	250	50 A @ 250 VAC	.0511	18.50	117	X
	2.50	02.5	250	50 A @ 250 VAC	.0392	22.20	156	X
	3.00	003.	250		.0276	59.29	103	X
	3.50	03.5	250		.0199	59.34	87	X
1	4.00	004.	250		.0160	68.10	83	X
í	5.00	005.	250		.0115	122.39	73	X

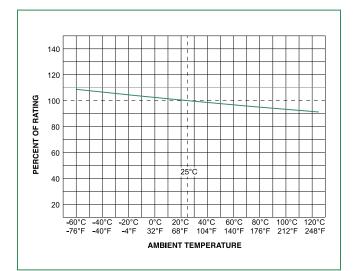
Notes:

- 1. Cold resistance measured at less than 10% of rated current at 23°C.
- 2. Agency Approval Table Key: X=Approved or Certified, P=Pending.

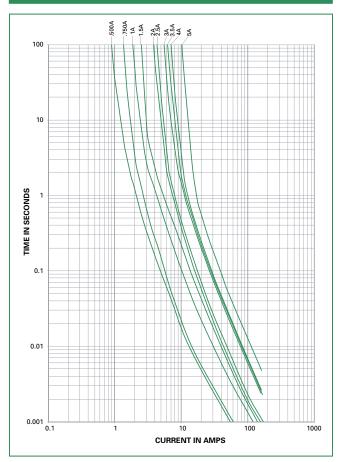




Temperature Rerating Curve

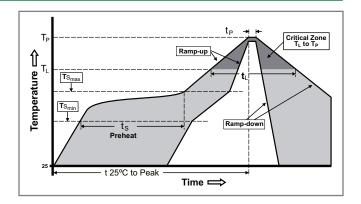


Average Time Current Curves



Soldering Parameters

Reflow Co	ndition	Pb-free assembly	
	-Temperature Min (T _{s(min)})	150°C	
Pre Heat	-Temperature Max (T _{s(max)})	200°C	
	-Time (Min to Max) (t _s)	60 – 180 seconds	
Average R (T _L) to pea	amp-up Rate (Liquidus Temp k)	5°C/second max.	
T _{S(max)} to T _L - Ramp-up Rate		5°C/second max.	
Reflow	-Temperature (T _L) (Liquidus)	217°C	
nellow	-Temperature (t _L)	60 – 150 seconds	
PeakTemperature (T _P)		250 ^{+0/-5} °C	
Time within 5°C of actual peak Temperature (t _p)		20 – 40 seconds	
Ramp-down Rate		5°C/second max.	
Time 25°C to peak Temperature (T _P)		8 minutes max.	
Do not exceed		260°C	





Product Characteristics

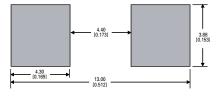
Materials	Body: Ceramic Cap: Silver-plated Brass		
Product Marking	Brand, Ampere Rating, Voltage Rating, UMF Logo		
Insulation Resistance (after Opening)	MIL-STD-202, Method 302, Test Condition A (10,000 ohms, Minimum)		
Solderability	MIL-STD-202, Method 208		
Resistance to Soldering Heat	MIL-STD-202, Method 210, Test Condition B (10 seconds at 260°C)		
Moisture Sensitivity Level	Level 1 J-STD-020C		

Operating Temperature	-55°C to 125°C with proper rerating		
Thermal Shock	MIL-STD-202F, Method 107G, Test Condition B (5 cycles, -65°C to 125°C)		
Vibration	MIL-STD-202F, Method 201A (10-55 Hz)		
Moisture Resistance	MIL-STD-202, Method 106, High Humidity (90-98%RH), Heat (65°C)		
Salt Spray	MIL-STD-202F, Method 101D, Test Condition B		
Mechanical Shock	MIL-STD-202, Method 213, Test Condition I (100 G's peak for 6 msecs.)		

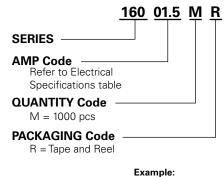
Dimensions

10.50 (0.429) 10.10 (0.389) 10

Recommended Pad Layout



Part Numbering System



1.5 amp product is 0160**01.5** MR

Packaging

Form Factor	Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code
Surface Mount	24mm Tape and Reel	EIA-RS 481-2 (IEC 286, part 3)	1000	MR



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